

## *Sensors and Materials Call for Papers*

### **Special Issue on Advanced Micro/Nanomaterials for Various Sensor Applications (Selected Papers from ICASI 2022)**

#### **Special Issue Information**

The 8th IEEE International Conference on Applied System Innovation 2022 (IEEE ICASI 2022, <https://2022.icas-conf.net/>) will be held in Sun Moon Lake, Nantou, Taiwan on April 22–23, 2022. The conference will provide a unified communication platform for a wide range of topics of electrical engineering, material science, and related fields.

Various sensors and flexible optoelectronics have been attracting a great deal of attention in recent years due to their potential applications in healthcare monitoring, biomedicine, electronic skin, wearable sensing technology, soft robotics, flat panel displays, safety equipment, smart systems, and future space applications. The aim of this special issue is to publish novel and high-quality research papers (experimental, theoretical, or simulation works) as well as review articles addressing recent advances in cutting-edge flexible electronics and sensors based on micro/nanomaterials. Research and review articles should provide a comprehensive insight into the characterization and understanding of functional micro/nanomaterial properties with the application of scanning techniques. Manuscripts submitted to *Sensors and Materials* must be not published previously or under consideration for publication elsewhere. Potential topics include, but are not limited to:

- Design, synthesis, and characterization of functional micro/nanomaterials for sensing applications and electronic devices
- Chemical and gas sensors based on micro/nano sensing materials  
Advanced materials for mechatronics applications
- Molecular dynamics simulations and quantum chemical calculations for micro/nanomaterials related to sensing applications and flexible electronics
- Theories and principles related to micro/nanomaterials, chemical and gas sensing, and flexible electronics
- Sensors and flexible electronics for future food and agricultural applications
- Advanced scanning techniques for characterization of sensors and flexible electronics

#### **Schedule**

Manuscript Due: July 31, 2023

First Round of Reviews: August 31, 2023

Second Round of Reviews: October 25, 2023

Acceptance of Final papers: November 30, 2023

Publication (planned): January 31, 2024

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(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in Sensors and Materials format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee (JPY 10000–30000 for electronic proofreading), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

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